

SMD CERAMIC ANTENNA Data Sheet

TS3216E245D05

For 2400-2484MHz 3.2x1.6mm [EIA1206]

TSUN SMD CERAMIC ANTENNA

FEATURES

- · Light weight, compact
- · Wide bandwidth, lowcost
- · Built-in antenna with high gain

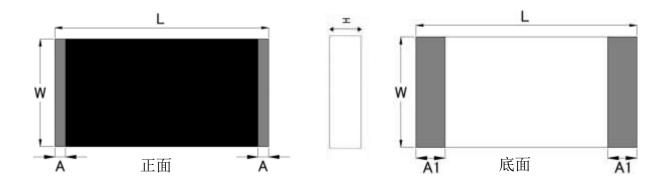
APPLICATIONS

- · Bluetooth
- · IEEE802.11g/b
- · Zigbee systems,etc...



TS3216E245D05

SHAPES AND DIMENSIONS Dimensions in mm



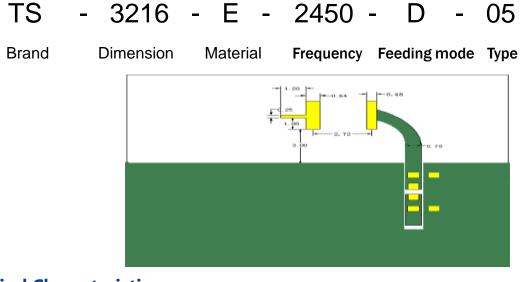
L	W	А	A 1	Η
3. 2 ± 0. 1	1. 6 ± 0. 1	0. 1 5±0. 05	0 . 4 ±0 . 15	0. 55±0.1

*切記: SMT貼片需黑色面朝上

Electrical Characteristics per line(TA=25°C)

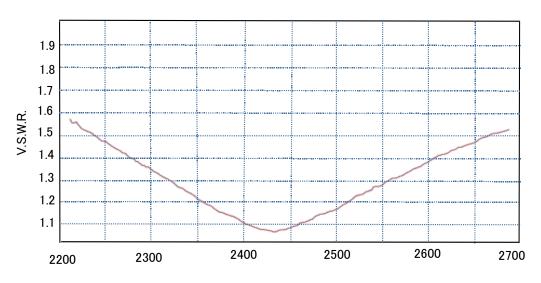
Parameter	Specification	Units
Frequency Band	2400~2483	MHz
Polarization	Linear	
Peak Gain	0.98	dBi
Peak Efficiency	68.8%	%
Impendance	50	Ω

PART NUMBERING SYSTEM



Typical Characteristics

Fig.1 VSWR

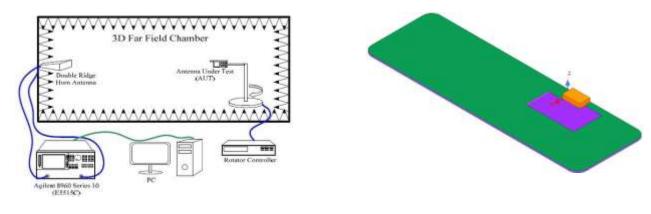


Frequency [MHz]

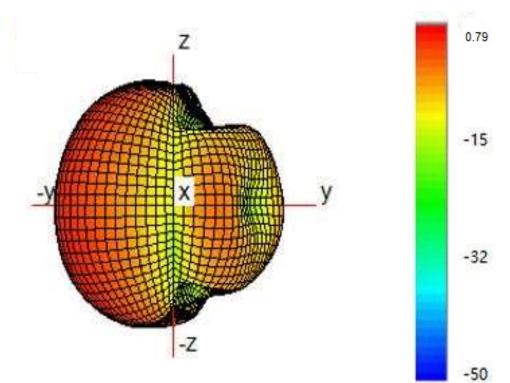
Radiation Pattern

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.

Fig.2 FAR-field Chamber

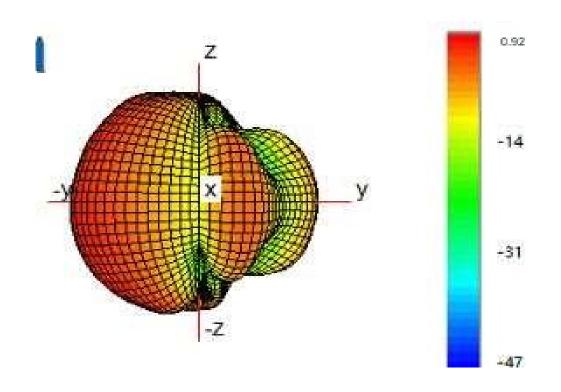


3D Gain Pattern (2400 MHz)

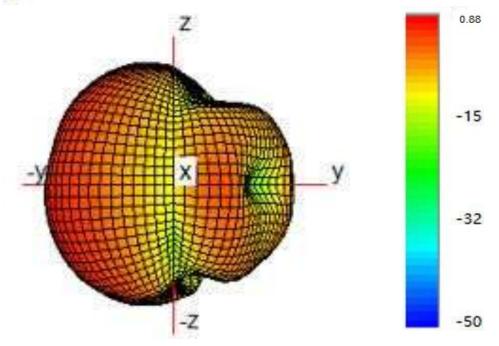


TSUN SMD CERAMIC ANTENNA

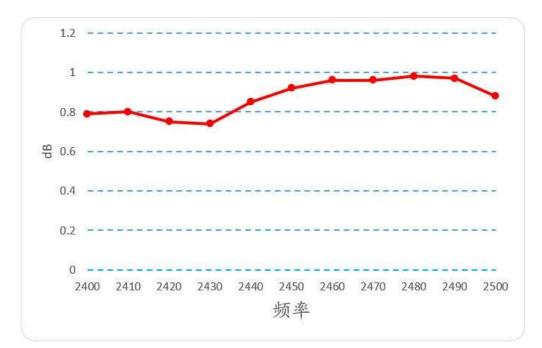
3D G ain Pattern (2450 M Hz)



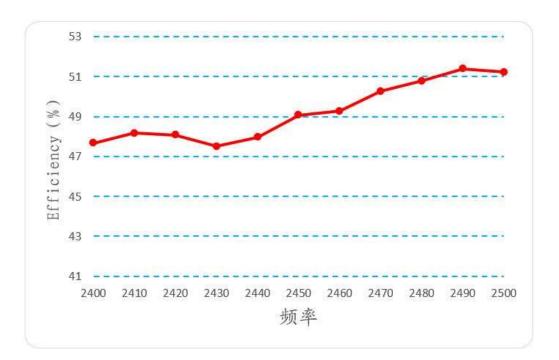
$3\,D$ G ain Pattern (2500 MHz)



Gain (dBi)



Eiciency (%)



Item	Condition	Specification
Thermal shock	 30±3 minutes at -40°C±5°C, Convert to +105°C (5 minutes) 30±3 minutes at +105°C±5°C, Convert to -40°C (5 minutes) Total 100 continuous cycles 	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: 85±5°C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	No apparent damage Fulfill the electrical spec. after test.	1. Temperature: 150°C±5°C 2. Time: 1000 hours.
Low temperature resistance	1. Temperature: -40°C±5°C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	oldering heat resistance1. Solder bath temperature : 260±5°C2. Bathing time: 10±1 seconds	
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of 245 ± 5 °C for 3 ± 1 seconds.	No apparent damage

(2)) Storage Condition

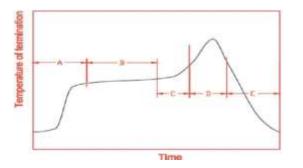
(a) At warehouse: The temperature should be within $0 \sim 30^{\circ}$ C and humidity should be less than 60% RH.The product should be used within 1 year from the time of elivery.

(b) On board: The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40°C to +85°C.

Recommended Reflow Solder curve



A	1 ^e rising temperature	The normal to Preheating temperature	30s to 60s
В	Preheating	140°C to 160°C	60s to 120s
C	2 ^{re} rising temperature	Preheating to 200°C	20s to 40s
		# 22010	50s~-60s
		# 230°C	40s~50s
D	Main heating	# 240°C	30s~40s
		# 250°C	20s~40s
		if 260°C	20s~40s
Ē	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s

(1)) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

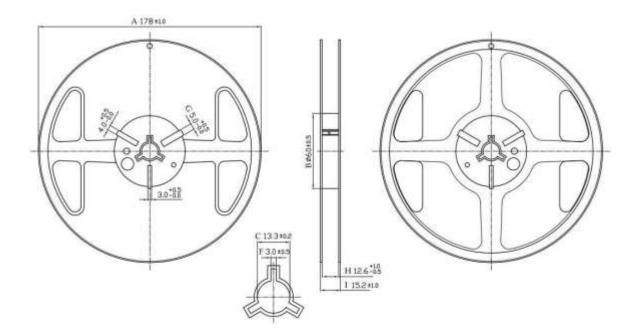
- (a) The tip temperature must be less than 350°C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

(2)Soldering Volume

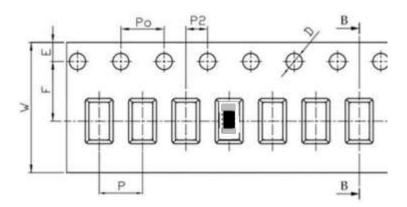
Note that excess of soldering volume will easily get crack the body of this product.

PACKAGING STYLE

REEL DIMENSIONS



□ TAPE DIMENSIONS



Feature	Specifications	Tolerances
W	00. 8	±0.30
Р	4.00	±0.10
E	1.75	±0.10
F	3.50	±0.10
P2	2.00	±0.10
D	1.50	+0.10 -0.00
Po	4.00	±0.10
10Po	40.00	±0.20

Typing Quantity: 5000 pieces per 7" reel

Order Information

Device	Package	Net Weight	Carrier	Quantity	HSF Status
TS3216E245D05	3216	0.0089g	Tape&Reel	5000pcs	RoHS compliant

Revision history

Date	Revision	Description of changes
2018-11-5	1.0	First Version
2022-12-9	1.1	Update the package information

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